

# EPO-TEK® H44

Epoxy; Epoxide  
Epoxy Technology Inc.

Message:  
EPO-TEK® H44 is a single component, gold-filled, electrically conductive epoxy adhesive designed for hybrid microelectronic packaging.

General Information			
Filler / Reinforcement	Gold		
Features	Electrically Conductive		
	High Viscosity		
	Low to No Outgassing		
Uses	Adhesives		
	Aerospace Applications		
	Electrical/Electronic Applications		
	Medical/Healthcare Applications		
Agency Ratings	ASTM E 595		
	EC 1907/2006 (REACH)		
	EU 2003/11/EC		
	EU 2006/122/EC		
RoHS Compliance	RoHS Compliant		
Forms	Paste		
Physical	Nominal Value	Unit	
Particle Size	< 50.0	µm	
Degradation Temperature	388	°C	TGA
Die Shear Strength - >10 kg (23°C)	23.4	MPa	
Operating Temperature			
Continuous	-55 to 200	°C	
Intermittent	-55 to 300	°C	
Weight Loss on Heating (300°C)	0.060	%	
Thermal	Nominal Value	Unit	
Glass Transition Temperature <sup>1</sup>	> 100	°C	
Thermoset	Nominal Value	Unit	Test Method
Shelf Life (23°C)	26	wk	
Uncured Properties	Nominal Value	Unit	Test Method
Color	Brown		
Viscosity <sup>2</sup> (23°C)	> 820	Pa · s	
Curing Time (150°C)	1.0	hr	

Cured Properties	Nominal Value	Unit	Test Method
Volume Resistivity (23°C)	< 5.0E-4	ohms·cm	
NOTE			
1.	Dynamic Cure 20-200°C/ISO 25 Min; Ramp -10-200°C @ 20°C/Min		
2.	0.5 rpm		

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#### Recommended distributors for this material

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